

## FEATURES

- Member of the Texas Instruments Widebus™ Family
- Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## DESCRIPTION/ORDERING INFORMATION

This 1-bit to 4-bit address register/driver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The device is ideal for use in applications in which a single address bus is driving four separate memory locations. The SN74ALVCH162831 can be used as a buffer or a register, depending on the logic level of the select ( $\overline{SEL}$ ) input.

When  $\overline{SEL}$  is logic high, the device is in the buffer mode. The outputs follow the inputs and are controlled by the two output-enable ( $\overline{OE}$ ) inputs. Each  $\overline{OE}$  controls two groups of nine outputs.

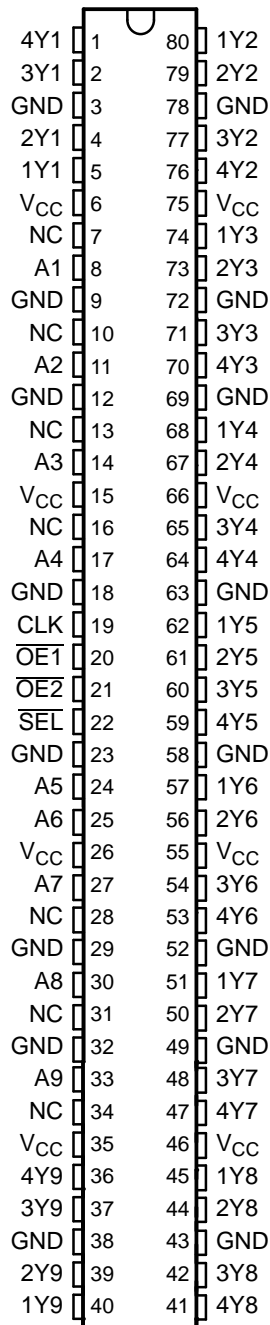
When  $\overline{SEL}$  is logic low, the device is in the register mode. The register is an edge-triggered D-type flip-flop. On the positive transition of the clock (CLK) input, data set up at the A inputs is stored in the internal registers.  $\overline{OE}$  controls operate the same as in buffer mode.

When  $\overline{OE}$  is logic low, the outputs are in a normal logic state (high or low logic level). When  $\overline{OE}$  is logic high, the outputs are in the high-impedance state.

$\overline{SEL}$  and  $\overline{OE}$  do not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The outputs, which are designed to sink up to 12 mA, include equivalent 26-Ω resistors to reduce overshoot and undershoot.

DBB PACKAGE  
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

# SN74ALVCH162831 1-BIT TO 4-BIT ADDRESS REGISTER/DRIVER WITH 3-STATE OUTPUTS

SCES084H–AUGUST 1996–REVISED SEPTEMBER 2004

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

## ORDERING INFORMATION

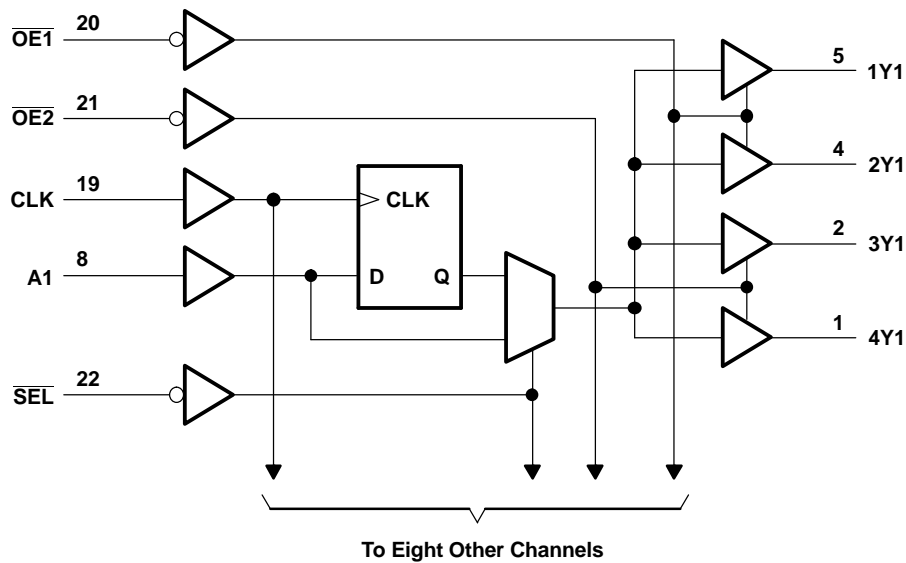
$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TVSOP - DBB	Tape and reel	SN74ALVCH162831GR	ALVCH162831

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE

INPUTS				OUTPUT Y
$\overline{OE}$	SEL	CLK	A	
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H

## LOGIC DIAGRAM (POSITIVE LOGIC)



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	4.6	V
$V_O$	Output voltage range <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		-50 mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50 mA
$I_O$	Continuous output current		±50	mA
	Continuous current through each $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>		64	°C/W
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	1.65	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2	
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	0.8	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$	-2	mA
		$V_{CC} = 2.3\text{ V}$	-6	
		$V_{CC} = 2.7\text{ V}$	-8	
		$V_{CC} = 3\text{ V}$	-12	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$	2	mA
		$V_{CC} = 2.3\text{ V}$	6	
		$V_{CC} = 2.7\text{ V}$	8	
		$V_{CC} = 3\text{ V}$	12	
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
$T_A$	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74ALVCH162831

## 1-BIT TO 4-BIT ADDRESS REGISTER/DRIVER

### WITH 3-STATE OUTPUTS

SCES084H–AUGUST 1996–REVISED SEPTEMBER 2004

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
	I <sub>OH</sub> = -2 mA	1.65 V	1.2			
	I <sub>OH</sub> = -4 mA	2.3 V	1.9			
	I <sub>OH</sub> = -6 mA	2.3 V	1.7			
		3 V	2.4			
	I <sub>OH</sub> = -8 mA	2.7 V	2			
I <sub>OH</sub> = -12 mA	3 V	2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2			V
	I <sub>OL</sub> = 2 mA	1.65 V	0.45			
	I <sub>OL</sub> = 4 mA	2.3 V	0.4			
	I <sub>OL</sub> = 6 mA	2.3 V	0.55			
		3 V	0.55			
	I <sub>OL</sub> = 8 mA	2.7 V	0.6			
I <sub>OL</sub> = 12 mA	3 V	0.8				
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5			μA
I <sub>I(hold)</sub>	V <sub>I</sub> = 0.58 V	1.65 V	25			μA
	V <sub>I</sub> = 1.07 V	1.65 V	-25			
	V <sub>I</sub> = 0.7 V	2.3 V	45			
	V <sub>I</sub> = 1.7 V	2.3 V	-45			
	V <sub>I</sub> = 0.8 V	3 V	75			
	V <sub>I</sub> = 2 V	3 V	-75			
	V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V	±500			
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	40			μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750			μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	4.5			pF
	Data inputs		5			
C <sub>o</sub>	Outputs	V <sub>O</sub> = V <sub>CC</sub> or GND	7.5			pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	(1)		150		150		150		MHz
t <sub>w</sub>	Pulse duration, CLK high or low	(1)		3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, A data before CLK↑	(1)		2		2		1.6		ns
t <sub>h</sub>	Hold time, A data after CLK↑	(1)		0.7		0.5		1.1		ns

(1) This information was not available at the time of publication.

**SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			(1)		150		150		150		MHz
$t_{pd}$	A	Y	(1)		1.1	4.7	4.8		1.5	4.3	ns
	CLK		(1)		1	5.3	5.3		1.4	4.7	
	$\overline{SEL}$		(1)		1.1	6	6.2		1.5	4.8	
$t_{en}$	$\overline{OE}$	Y	(1)		1	5.9	5.9		1.1	5.1	ns
$t_{dis}$	$\overline{OE}$	Y	(1)		1.4	6.3	5.4		1.6	5.1	ns

(1) This information was not available at the time of publication.

**SWITCHING CHARACTERISTICS**

 from 0°C to 65°C,  $C_L = 50\text{ pF}$ 

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\text{ V}$ $\pm 0.15\text{ V}$		UNIT
			MIN	MAX	
$t_{pd}$	CLK	Y	1.9	4.5	ns

**OPERATING CHARACTERISTICS**
 $T_A = 25^\circ\text{C}$ 

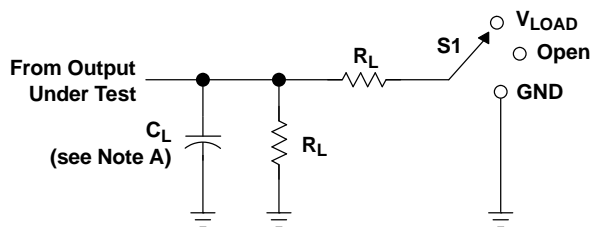
PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance per bit (four outputs switching)	All outputs enabled	(1)	119	132	pF
		All outputs disabled	(1)	22	25	

(1) This information was not available at the time of publication.

# SN74ALVCH162831 1-BIT TO 4-BIT ADDRESS REGISTER/DRIVER WITH 3-STATE OUTPUTS

SCES084H–AUGUST 1996–REVISED SEPTEMBER 2004

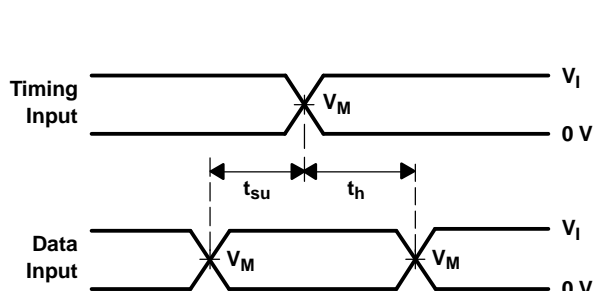
## PARAMETER MEASUREMENT INFORMATION



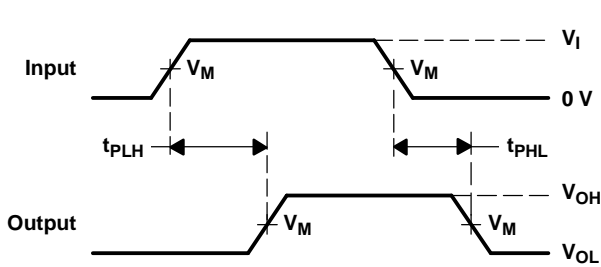
LOAD CIRCUIT

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

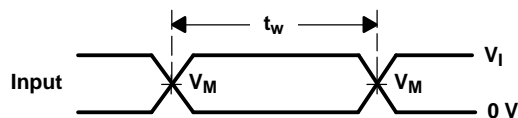
$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
1.8 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 V \pm 0.2 V$	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



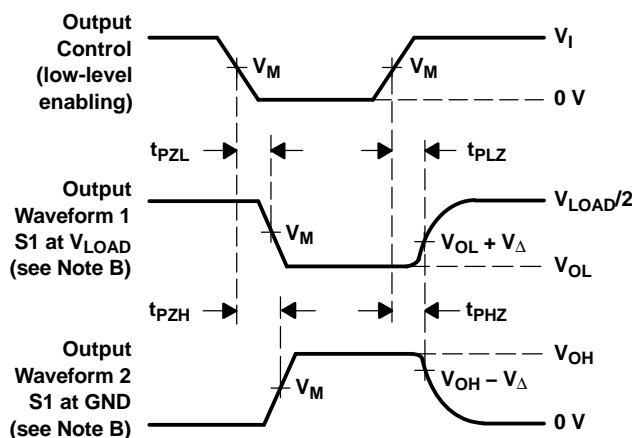
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVCH162831GRE4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH162831GRG4	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH162831DBBR	OBSOLETE	TSSOP	DBB	80		TBD	Call TI	Call TI
SN74ALVCH162831GR	ACTIVE	TSSOP	DBB	80	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

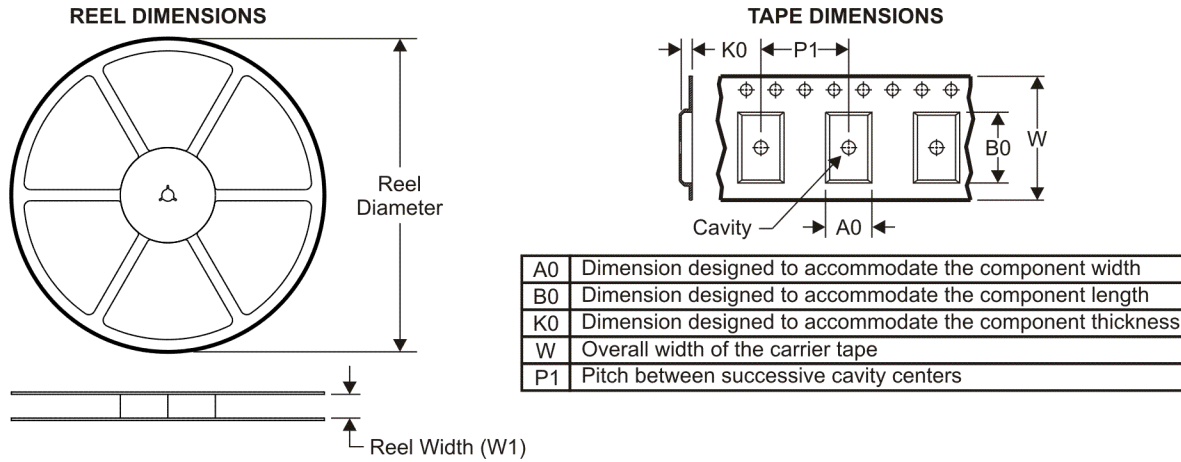
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

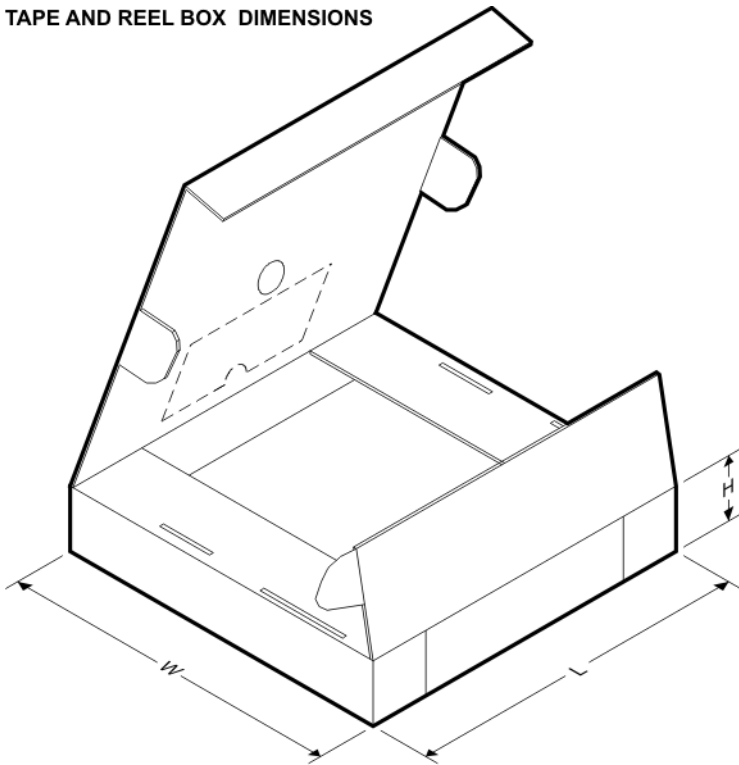


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH162831GR	TSSOP	DBB	80	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1



**TAPE AND REEL BOX DIMENSIONS**



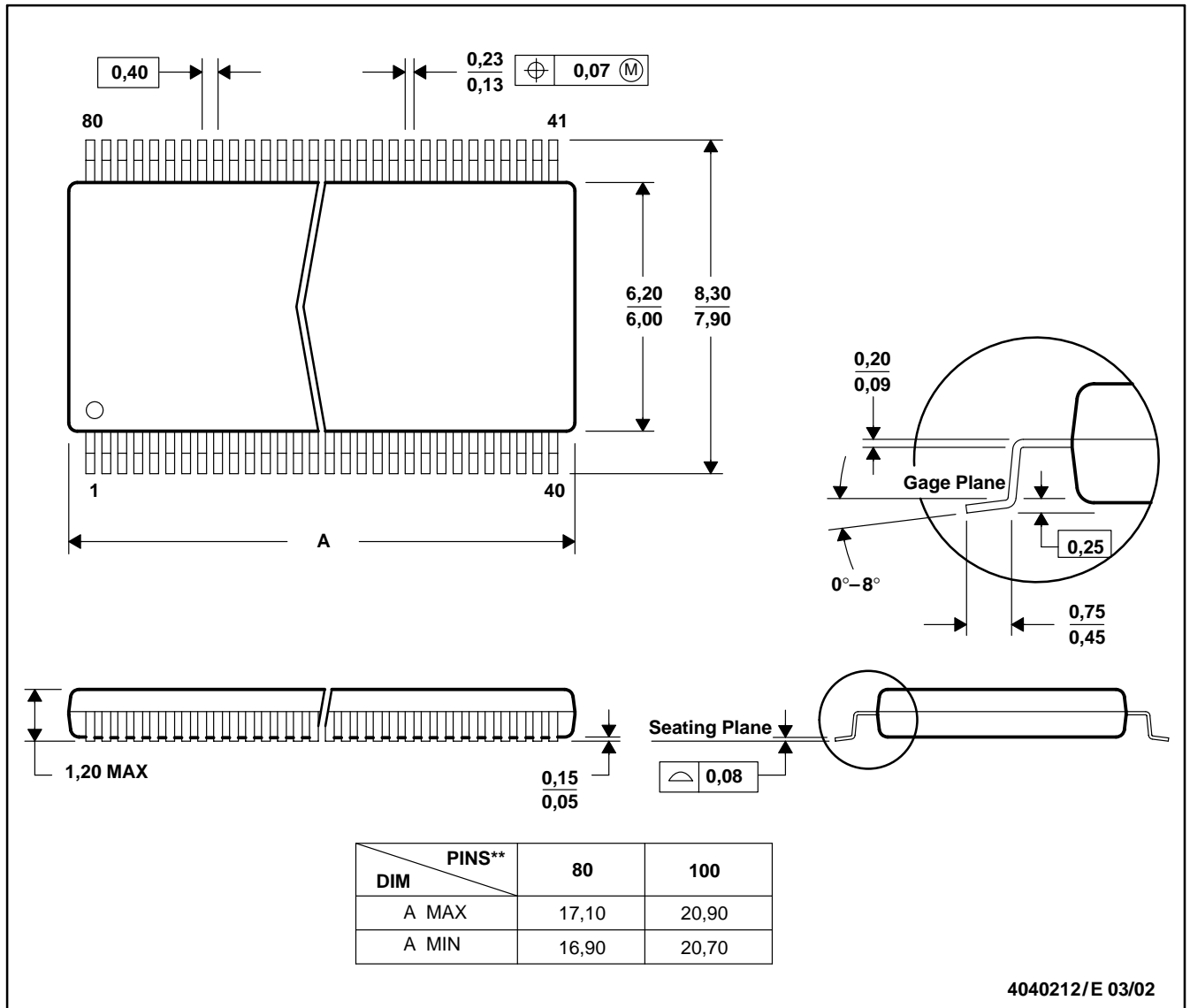
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH162831GR	TSSOP	DBB	80	2000	346.0	346.0	41.0

DBB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

80 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC : 80 Pin – MO-153 Variation FF  
 100 Pin – MO-194 Variation BB

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>

### Applications

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
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